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Dated: December 30, 2002

Signature: Steven A. Garner

(Steven A. Garner)

Docket No.: TESSERA 3.0-102 II DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Thomas H. DiStefano

Application No.: 09/628,049

Filed: July 27, 2000

For: PACKAGED MICROELECTRONIC
ELEMENTS WITH ENHANCED THERMAL
CONDUCTION

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: Group Art Unit: 2827
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: Examiner: D. Graybill
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Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the Official Action mailed August 28, 2002, applicant submits the following amendments and remarks.

IN THE SPECIFICATION

The following paragraph has been inserted on page 13, line 16 of the specification:

Fig. 9 is a fragmentary process flow chart.

The following paragraph has been inserted on page 31, line 19 of the specification:

Fig. 9 shows a portion of a process flow chart showing the process by which a curable liquid penetrates between the rear surface of the semiconductor chip and the top surface of the dielectric element. Step 1 shows placing a curable liquid on the top surface of the dielectric element at the edges of the chip. Step 2 involves applying gas under pressure to the curable liquid. Step 3 shows maintaining of the gas pressure.